#### 503722649 03/04/2016

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3769290

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
SATORU OKAMOTO	02/11/2016
SHINYA SASAGAWA	02/10/2016

## **RECEIVING PARTY DATA**

Name:	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.	
Street Address:	398, HASE	
City:	ATSUGI-SHI, KANAGAWA-KEN	
State/Country:	JAPAN	
Postal Code:	243-0036	

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	15056356

### CORRESPONDENCE DATA

Fax Number: (877)769-7945

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (202) 783-5070 Email: APSI@fr.com Correspondent Name: JOHN F. HAYDEN

Address Line 1: FISH & RICHARDSON P.C.

Address Line 2: P.O.BOX 1022

Address Line 4: MINNEAPOLIS, MINNESOTA 55440-1022

ATTORNEY DOCKET NUMBER:	12732-1647001	
NAME OF SUBMITTER:	JANELLE A. JACKSON	
SIGNATURE:	/Janelle A. Jackson/	
DATE SIGNED:	03/04/2016	

**Total Attachments: 1** 

source=12732-1647001 Assignment#page1.tif

**PATENT REEL: 037895 FRAME: 0988** 

503722649

## **ASSIGNMENT**

For valuable consideration, We, <u>Satoru OKAMOTO of Isehara, Kanagawa, Japan and Shinya SASAGAWA of Chigasaki, Kanagawa, Japan</u> hereby assign to <u>Semiconductor Energy Laboratory Co., Ltd.,</u> a <u>Japanese</u> corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF, filed February 29, 2016 , and assigned U.S. Serial Number 15/056,356 , and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature

Name: Satoru OKAMOTO

Date: 02/11/20/6

Signature Shinya Sasagawa

Name: Shinya SASAGAWA

Date: 02/10/20/6

RECORDED: 03/04/2016

PATENT REEL: 037895 FRAME: 0989